Features

- Radial leaded Devices
- Cured,flame retardant epoxy polymer insulating material meets UL94V-0 requirements
- Bulk packaging,or tape and reel available on most models
- Agency Approval:ROHS

Applications

Almost anywhere there is a low voltage power supply, up to DC60V and a load to be protested, including:

- Telecommumications system
- Network switching
- Power transformers
- Communication equipment

Dimensions

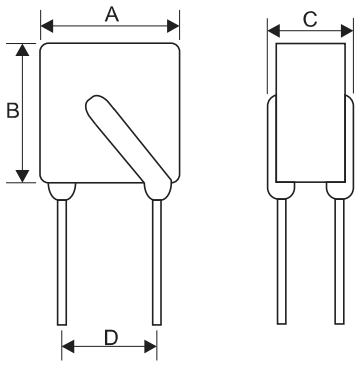


Fig 1

Dimensions in millimerters

Part Number	Fig	A(max.)	B(max.)	C(max.)	D(typ.)
JK600-110U	1	14.0	14.0	6	5.1
JK600-150U	1	14.0	14.0	6	5.1
JK600-160U	1	14.0	14.0	6	5.1

Physical Characteristcs

Material:Leads	
All	Tin plated copper,22AWG,0.60mm

Electrical Characteristics(25℃)

Part Number	I_{hold} (A)	I_{trip} (A)	$V_{max.}$ OP (Vdc)	$V_{max.}$ Interrupt (Vrms)	$I_{max.}$ (A)	$P_{d\ max.}$ (W)	Maximum Time To Trip		Resistance		
							Current (A)	Time (Sec.)	$R_{min.}$ (Ω)	$R_{max.}$ (Ω)	$R1_{max.}$ (Ω)
JK600-110U	0.11	0.22	60	600	3	1	1	8	6	16	24
JK600-150U	0.15	0.30	60	600	3	1	1	9	5	14	22
JK600-160U	0.16	0.32	60	600	3	1	1	10	4	12	18

Notes :

I_{hold} = Hold Current. Maximum current device will not trip in 25°C still air.

I_{trip} = Trip Current. Minimum current at which the device will always trip in 25°C still air.

V_{max}OP = Maximum operating volatge(Vdc) device can withstand without damage at ratde current(Imax).

V_{max}Interrupt = Maximum interrupt volatge(Vac) device can withstand without damage at ratde current.

I_{max} = Maximum fault current device can withstand without damage at rated voltage (Vmax).

P_d = Typical power dissipatde from device when in the tripped state in 25°C still air.

R_{min} = Minimum device resistance prior to tripping at 25°C.

R_{max} = Maximum device resistance prior to tripping at 25°C.

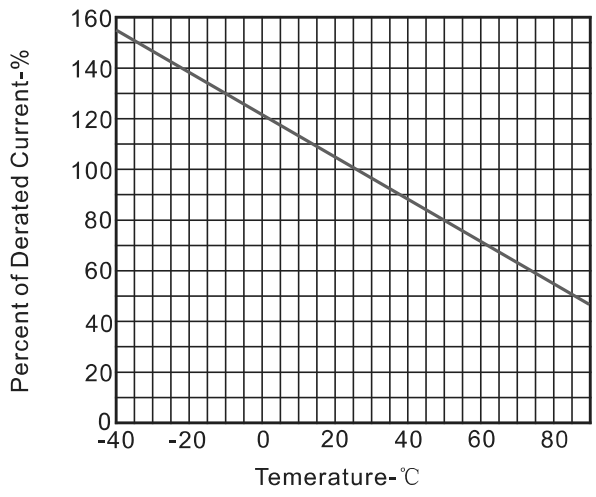
$R1_{max}$ = Maximum device resistance one hour after it is trippde at 25°C.

CAUTION : Operation beyond the specified ratings may result in damage and possible arcing.

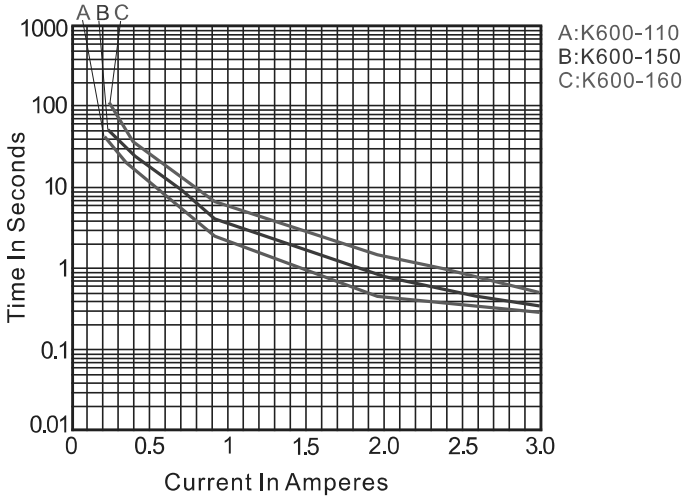
Thermal Derating Chart-I_{hold}(A)

Maximum ambient operating temperature (T_{mao})vs.hold current (I_{hold})									
Part Number	-40°C	-20°C	0°C	25°C	40°C	50°C	60°C	70°C	85°C
JK600-110U	0.175	0.152	0.131	0.11	0.09	0.08	0.07	0.06	0.046
JK600-150U	0.238	0.207	0.179	0.15	0.125	0.11	0.096	0.083	0.063
JK600-160U	0.254	0.221	0.190	0.16	0.133	0.117	0.102	0.088	0.067

Thermal Derating Curve



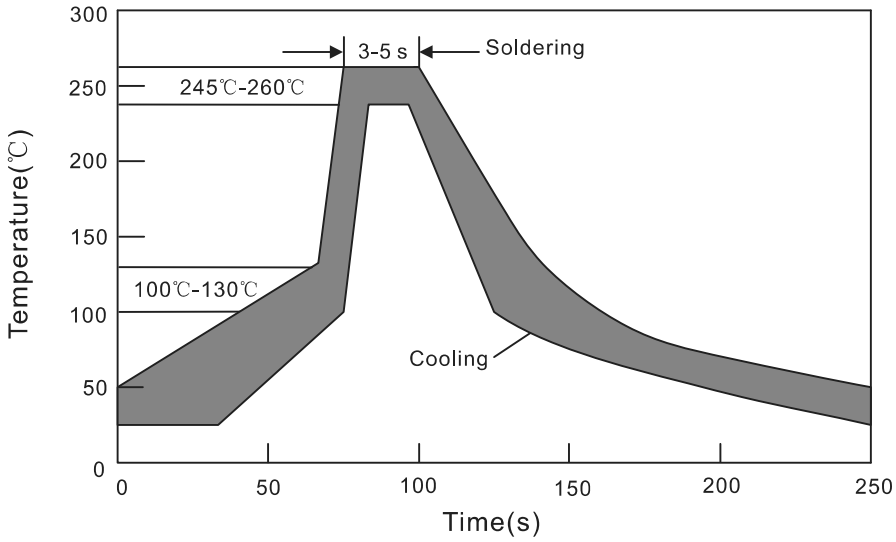
Typical Time To Trip At 25°C



Environmental Specifications

Test	Conditions	Resistance Change
Passive aging	+85°C, 1000 hrs.	±8% typical
Humidity aging	+85°C, 85% R.H. , 168 hours	±8% typical
Thermal shock	+125°C to -55°C, 10 times	±12% typical
Resistance to solvent	MIL-STD-202,Method 215	No change
Vibration	MIL-STD-202,Method 201	No change
Ambient operating conditions : - 40 °C to +85 °C		

Recommended Soldering Conditions



Items	Conditions
Pre-Heating Zone	Refer to the condition recommended by the flux manufacturer. Maximum ramping rate should not exceed 4℃/sec.
Soldering Zone	Maximum solder temperature should not exceed 260℃.
Cooling Zone	Forced cooling.

Packageing Information

Part Number	Packaging Option	Quantity
JK600-110U~160U	Bulk	200pcs per bag